

Electronic Patent Application Fee Transmittal

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|---|--|-----------------|---------------|-----------------------------|
| Application Number: | 10666399 | | | |
| Filing Date: | 18-Sep-2003 | | | |
| Title of Invention: | Molded chip fabrication method and apparatus | | | |
| First Named Inventor/Applicant Name: | Michael S. Leung | | | |
| Filer: | Brian J. Philpott/Eleanor Nakada | | | |
| Attorney Docket Number: | P0298US-7 | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Claims in excess of 20 | 1202 | 4 | 50 | 200 |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-----------------------------------|----------|----------|--------|----------------------|
| Extension - 1 month with \$0 paid | 1251 | 1 | 120 | 120 |
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 320 |